PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data	
1.1 Company	STMicroelectronics International N.V
1.2 PCN No.	ANALOG MEMS SENSORS/26/16623
1.3 Title of PCN	ST Manufacturing Reshaping (Analog_BCD8sP_AG200 to SG8E_all: Qualification of SG8 (Singapore) as new FE Location.
1.4 Product Category	Please refer to the impacted Products list
1.5 Issue date	2026-11-04

2. PCN Team	
2.1 Contact supplier	
2.1.1 Name	ROBERTSON HEATHER
2.1.2 Phone	+1 8475853058
2.1.3 Email	heather.robertson@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Francesco MACINA
2.1.2 Marketing Manager	Lionel GRILLO
2.1.3 Quality Manager	Paolo MORETTI

3. Change		
3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Manufacturing reshaping program	Manufacturing reshaping program	New Front End = Singapore (Singapore)

4. Description of change		
	Old	New
4.1 Description	Front End = Agrate 200 (Italy)	Front End = Singapore (Singapore)
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	No impact	

5. Reason / motivation for change	
5.1 Motivation	In the frame of ST manufacturing reshaping program (refer to Corporate PCI 15383 - Early Notification), following the continuous improvement of our service and to increase production Capacity, ST Microelectronics is announcing the qualification of Singapore as Front End Location for the impacted Products in BCD8sP Technology. Please be advised that the enclosed list of products and dates could be subject to change. Such modifications may occur as part of the ongoing transformation program and will be communicated as and when available.
5.2 Customer Benefit	SERVICE CONTINUITY

6. Marking of parts / traceability of change	
6.1 Description	Traceability of change will be ensured by an internal codification (Finished Good/Type) printed on the carton box label.

7. Timing / schedule	
7.1 Date of qualification results	2028-01-28
7.2 Intended start of delivery	2028-07-28
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation			
8.1 Description			
8.2 Qualification report and qualification results	In progress	Issue Date	

9. Attachments (additional documentations)
16623 Public product.pdf 16623 Qualification Plan Detail_BCD8sP_AG200 to SG8E_all 16623.pdf

10. Affected parts		
10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	TSB582IDT	
	TSB582IQ2T	
	TSB582IYDT	
	TSB582IYQ2T	
	TSX582IYDT	

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